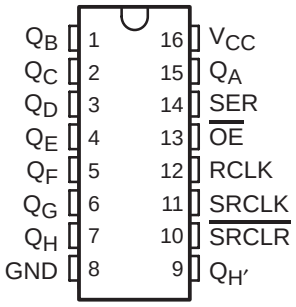
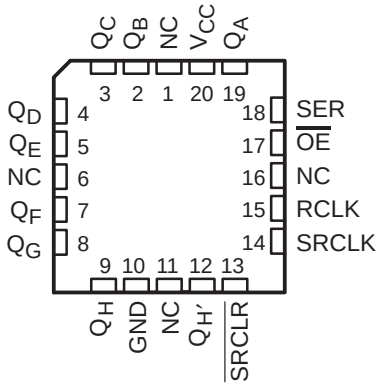
- **Operating Range 2-V to 5.5-V V_{CC}**
- **8-Bit Serial-In, Parallel-Out Shift**
- **Shift Register Has Direct Clear**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

SN54AHC595 . . . J OR W PACKAGE
SN74AHC595 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AHC595 . . . FK PACKAGE
(TOP VIEW)



NC − No internal connection

description/ordering information

The ’AHC595 devices contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state outputs. Separate clocks are provided for both the shift and storage registers. The shift register has a direct overriding clear ($\overline{SRCLR}$) input, serial (SER) input, and a serial output for cascading. When the output-enable ($\overline{OE}$) input is high, all outputs, except $Q_{H'}$, are in the high-impedance state.

Both the shift-register clock (SRCLK) and storage-register clock (RCLK) are positive-edge triggered. If both clocks are connected together, the shift register always is one clock pulse ahead of the storage register.

ORDERING INFORMATION

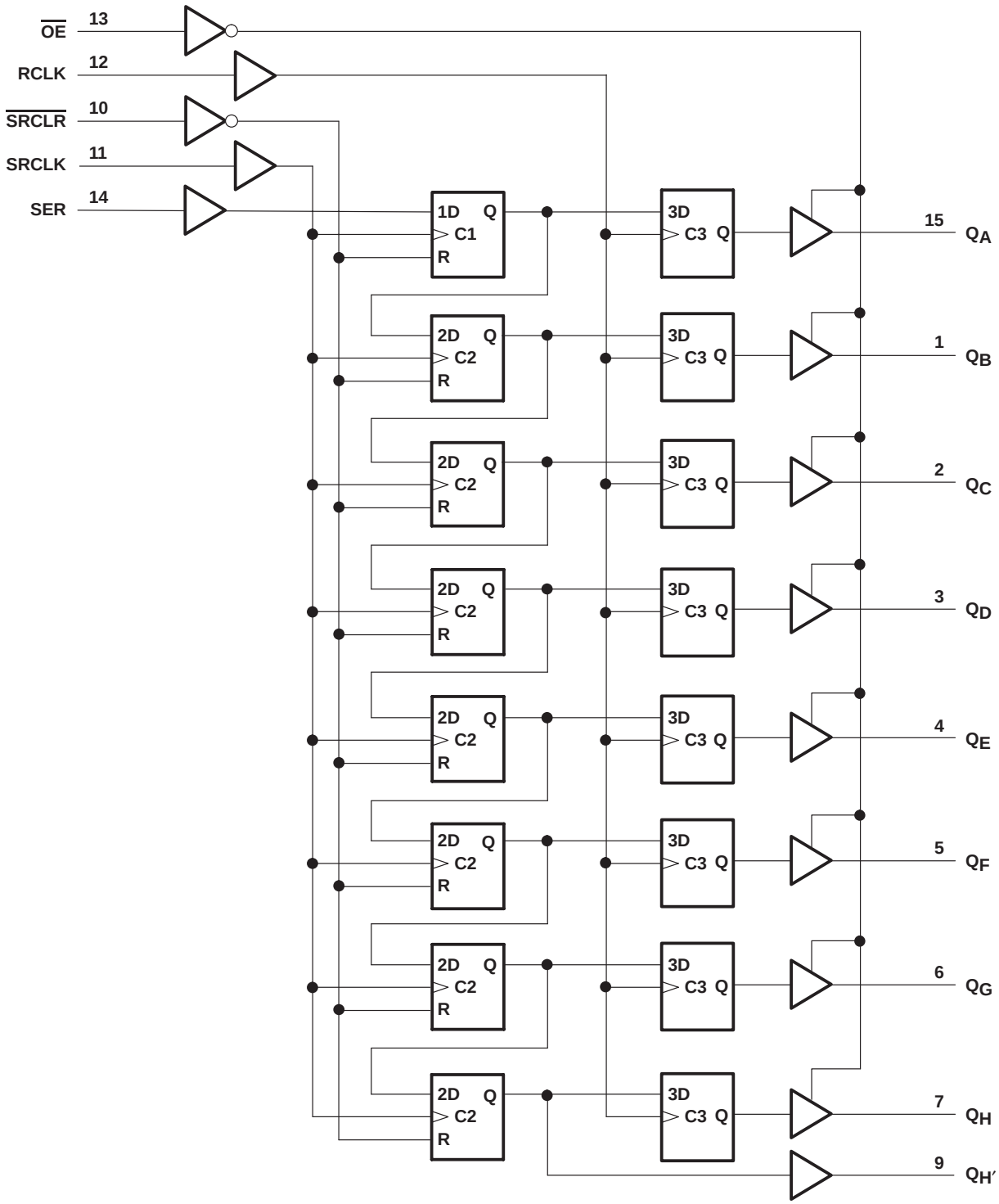
T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	PDIP − N	Tube	SN74AHC595N	SN74AHC595N
	SOIC − D	Tube	SN74AHC595D	AHC595
		Tape and reel	SN74AHC595DR	
	SOP − NS	Tape and reel	SN74AHC595NSR	AHC595
	SSOP − DB	Tape and reel	SN74AHC595DBR	HA595
	TSSOP − PW	Tube	SN74AHC595PW	HA595
		Tape and reel	SN74AHC595PWR	
−55°C to 125°C	CDIP − J	Tube	SNJ54AHC959J	SNJ54AHC595J
	CFP − W	Tube	SNJ54AHC595W	SNJ54AHC595W
	LCCC − FK	Tube	SNJ54AHC595FK	SNJ54AHC595FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

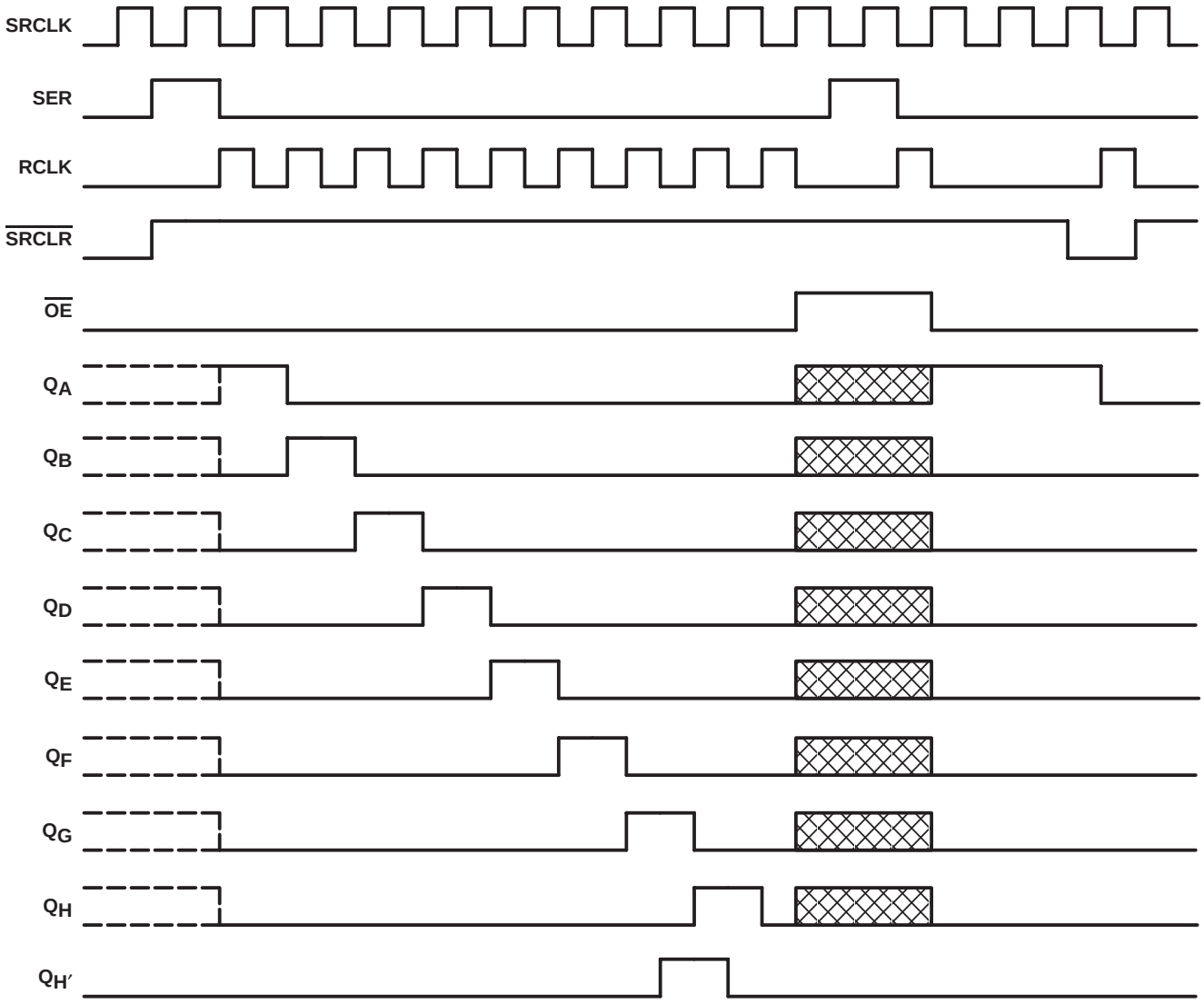
INPUTS					FUNCTION
SER	SRCLK	$\overline{\text{SRCLR}}$	RCLK	$\overline{\text{OE}}$	
X	X	X	X	H	Outputs Q_A–Q_H are disabled.
X	X	X	X	L	Outputs Q_A–Q_H are enabled.
X	X	L	X	X	Shift register is cleared.
L	↑	H	X	X	First stage of the shift register goes low. Other stages store the data of previous stage, respectively.
H	↑	H	X	X	First stage of the shift register goes high. Other stages store the data of previous stage, respectively.
X	X	X	↑	X	Shift-register data is stored into the storage register.

logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

timing diagram



NOTE: ⊠ implies that the output is in 3-State mode.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to 7 V
Output voltage range, V_O (see Note 1) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0) . . . . . −20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±25 mA
Continuous current through V_{CC} or GND . . . . . ±75 mA
Package thermal impedance, θ_{JA} (see Note 2): D package . . . . . 73°C/W
DB package . . . . . 82°C/W
N package . . . . . 67°C/W
NS package . . . . . 64°C/W
PW package . . . . . 108°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54AHC595		SN74AHC595		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5		1.5		V
		V_{CC} = 3 V	2.1		2.1		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5		0.5	V
		V_{CC} = 3 V		0.9		0.9	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2 V		−50		−50	μA
		V_{CC} = 3.3 V ± 0.3 V		−4		−4	mA
		V_{CC} = 5 V ± 0.5 V		−8		−8	
I_{OL}	Low-level output current	V_{CC} = 2 V		50		50	μA
		V_{CC} = 3.3 V ± 0.3 V		4		4	mA
		V_{CC} = 5 V ± 0.5 V		8		8	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 3.3 V ± 0.3 V		100		100	ns/V
		V_{CC} = 5 V ± 0.5 V		20		20	
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C			SN54AHC595		SN74AHC595		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = −50 μA		2 V	1.9	2		1.9		1.9		V
			3 V	2.9	3		2.9		2.9		
			4.5 V	4.4	4.5		4.4		4.4		
	I_{OH} = −4 mA		3 V	2.58			2.48		2.48		
	I_{OH} = −8 mA		4.5 V	3.94			3.8		3.8		
V_{OL}	I_{OL} = 50 μA		2 V			0.1		0.1		0.1	V
			3 V			0.1		0.1		0.1	
			4.5 V			0.1		0.1		0.1	
	I_{OL} = 4 mA		3 V			0.36		0.5		0.44	
	I_{OL} = 8 mA		4.5 V			0.36		0.5		0.44	
I_I	V_I = 5.5 V or GND		0 V to 5.5 V			±0.1		±1*		±1	μA
I_{OZ}	V_I = V_{CC} or GND, V_O = V_{CC} or GND, $\overline{OE}$ = V_{IH} or V_{IL}	Q_A–Q_H	5.5 V			±0.25		±2.5		±2.5	μA
I_{CC}	V_I = V_{CC} or GND,	I_O = 0	5.5 V			4		40		40	μA
C_i	V_I = V_{CC} or GND		5 V		3	10				10	pF
C_o	V_O = V_{CC} or GND		5 V		5.5						pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54AHC595		SN74AHC595		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	SRCLK high or low	5		5		5		ns
		RCLK high or low	5		5		5		
		$\overline{SRCLR}$ low	5		5		5		
t_{su}	Setup time	SER before SRCLK↑	3.5		3.5		3.5		ns
		SRCLK↑ before RCLK↑†	8		8.5		8.5		
		$\overline{SRCLR}$ low before RCLK↑	8		9		9		
		$\overline{SRCLR}$ high (inactive) before SRCLK↑	3		3		3		
t_h	Hold time	SER after SRCLK↑	1.5		1.5		1.5		ns

† This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54AHC595		SN74AHC595		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	SRCLK high or low	5		5		5		ns
		RCLK high or low	5		5		5		
		$\overline{\text{SRCLR}}$ low	5		5		5		
t_{su}	Setup time	SER before SRCLK↑	3		3		3		ns
		SRCLK↑ before RCLK↑†	5		5		5		
		$\overline{\text{SRCLR}}$ low before RCLK↑	5		5		5		
		$\overline{\text{SRCLR}}$ high (inactive) before SRCLK↑	2.5		2.5		2.5		
t_h	Hold time	SER after SRCLK↑	2		2		2		ns

† This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54AHC595		SN74AHC595		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	80*	120*		70*		70		MHz
			C_L = 50 pF	55	105		50		50		
t_{PLH}	RCLK	Q_A–Q_H	C_L = 15 pF		6*	11.9*	1*	13.5*	1	13.5	ns
t_{PHL}					6*	11.9*	1*	13.5*	1	13.5	
t_{PLH}	SRCLK	$Q_{H'}$	C_L = 15 pF		6.6*	13*	1*	15*	1	15	ns
t_{PHL}					6.6*	13*	1*	15*	1	15	
t_{PHL}	$\overline{\text{SRCLR}}$	$Q_{H'}$	C_L = 15 pF		6.2*	12.8*	1*	13.7*	1	13.7	ns
t_{PZH}	$\overline{\text{OE}}$	Q_A–Q_H	C_L = 15 pF		6*	11.5*	1*	13.5*	1	13.5	ns
t_{PZL}					7.8*	11.5*	1*	13.5*	1	13.5	
t_{PLH}	RCLK	Q_A–Q_H	C_L = 50 pF		7.9	15.4	1	17	1	17	ns
t_{PHL}					7.9	15.4	1	17	1	17	
t_{PLH}	SRCLK	$Q_{H'}$	C_L = 50 pF		9.2	16.5	1	18.5	1	18.5	ns
t_{PHL}					9.2	16.5	1	18.5	1	18.5	
t_{PHL}	$\overline{\text{SRCLR}}$	$Q_{H'}$	C_L = 50 pF		9	16.3	1	17.2	1	17.2	ns
t_{PZH}	$\overline{\text{OE}}$	Q_A–Q_H	C_L = 50 pF		7.8	15	1	17	1	17	ns
t_{PZL}					9.6	15	1	17	1	17	
t_{PHZ}	$\overline{\text{OE}}$	Q_A–Q_H	C_L = 50 pF		8.1	15.7	1	16.2	1	16.2	ns
t_{PLZ}					9.3	15.7	1	16.2	1	16.2	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

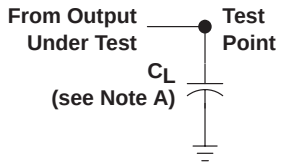
PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54AHC595		SN74AHC595		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	135*	170*		115*		115		MHz
			C_L = 50 pF	95	140		85		85		
t_{PLH}	RCLK	Q_A–Q_H	C_L = 15 pF		4.3*	7.4*	1*	8.5*	1	8.5	ns
t_{PHL}					4.3*	7.4*	1*	8.5*	1	8.5	
t_{PLH}	SRCLK	$Q_{H'}$	C_L = 15 pF		4.5*	8.2*	1*	9.4*	1	9.4	ns
t_{PHL}					4.5*	8.2*	1*	9.4*	1	9.4	
t_{PHL}	$\overline{SRCLR}$	$Q_{H'}$	C_L = 15 pF		4.5*	8*	1*	9.1*	1	9.1	ns
t_{PZH}	$\overline{OE}$	Q_A–Q_H	C_L = 15 pF		4.3*	8.6*	1*	10*	1	10	ns
t_{PZL}					5.4*	8.6*	1*	10*	1	10	
t_{PLH}	RCLK	Q_A–Q_H	C_L = 50 pF		5.6	9.4	1	10.5	1	10.5	ns
t_{PHL}					5.6	9.4	1	10.5	1	10.5	
t_{PLH}	SRCLK	$Q_{H'}$	C_L = 50 pF		6.4	10.2	1	11.4	1	11.4	ns
t_{PHL}					6.4	10.2	1	11.4	1	11.4	
t_{PHL}	$\overline{SRCLR}$	$Q_{H'}$	C_L = 50 pF		6.4	10	1	11.1	1	11.1	ns
t_{PZH}	$\overline{OE}$	Q_A–Q_H	C_L = 50 pF		5.7	10.6	1	12	1	12	ns
t_{PZL}					6.8	10.6	1	12	1	12	
t_{PHZ}	$\overline{OE}$	Q_A–Q_H	C_L = 50 pF		3.5	10.3	1	11	1	11	ns
t_{PLZ}					3.4	10.3	1	11	1	11	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

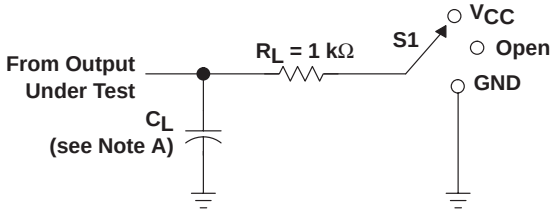
operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load, f = 1 MHz	25.2	pF

PARAMETER MEASUREMENT INFORMATION

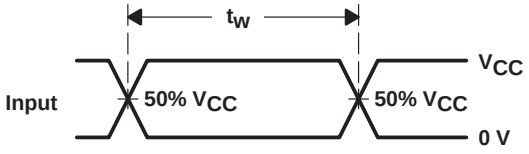


LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

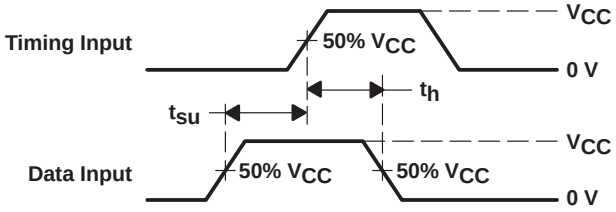


LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS

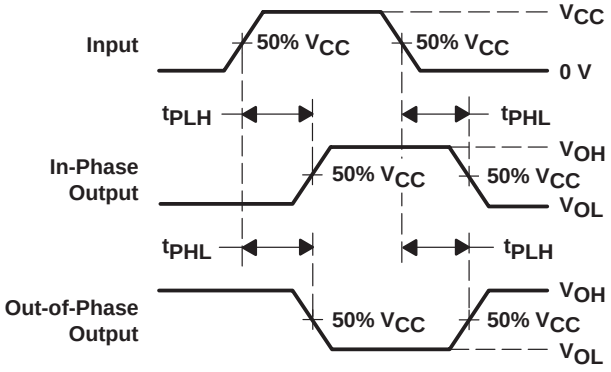
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}



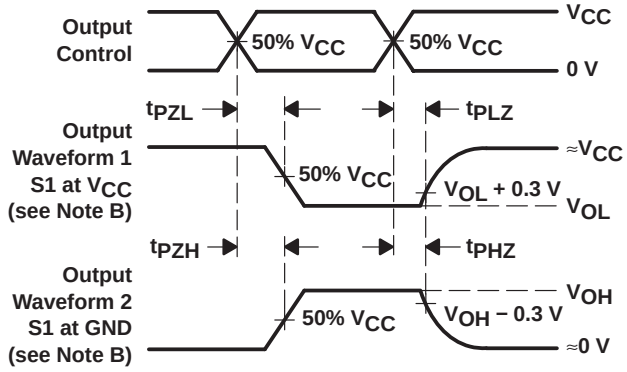
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
D. The outputs are measured one at a time, with one input transition per measurement.
E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74AHC595D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC595	Samples
SN74AHC595DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA595	Samples
SN74AHC595DBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA595	Samples
SN74AHC595DBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA595	Samples
SN74AHC595DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC595	Samples
SN74AHC595DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC595	Samples
SN74AHC595DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC595	Samples
SN74AHC595DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC595	Samples
SN74AHC595DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC595	Samples
SN74AHC595N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHC595N	Samples
SN74AHC595NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHC595N	Samples
SN74AHC595PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA595	Samples
SN74AHC595PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA595	Samples
SN74AHC595PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA595	Samples
SN74AHC595PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA595	Samples
SN74AHC595PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA595	Samples
SN74AHC595PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA595	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

OTHER QUALIFIED VERSIONS OF SN74AHC595 :

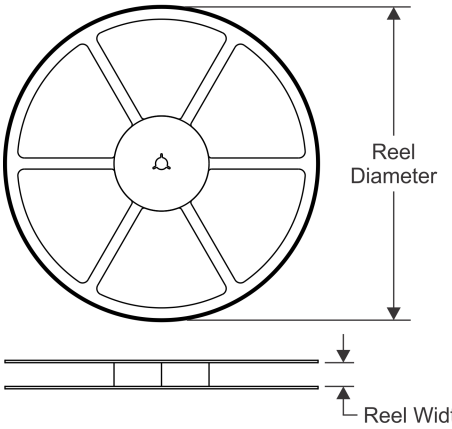
- Automotive: SN74AHC595-Q1

NOTE: Qualified Version Definitions:

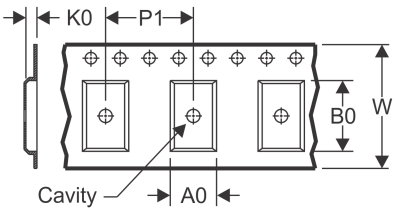
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

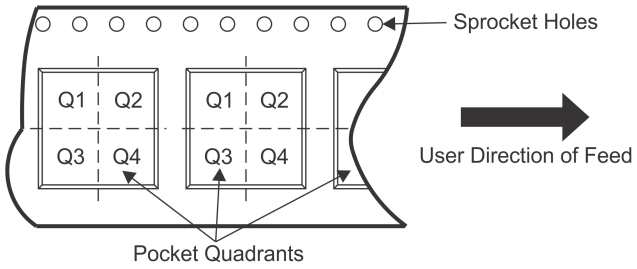


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

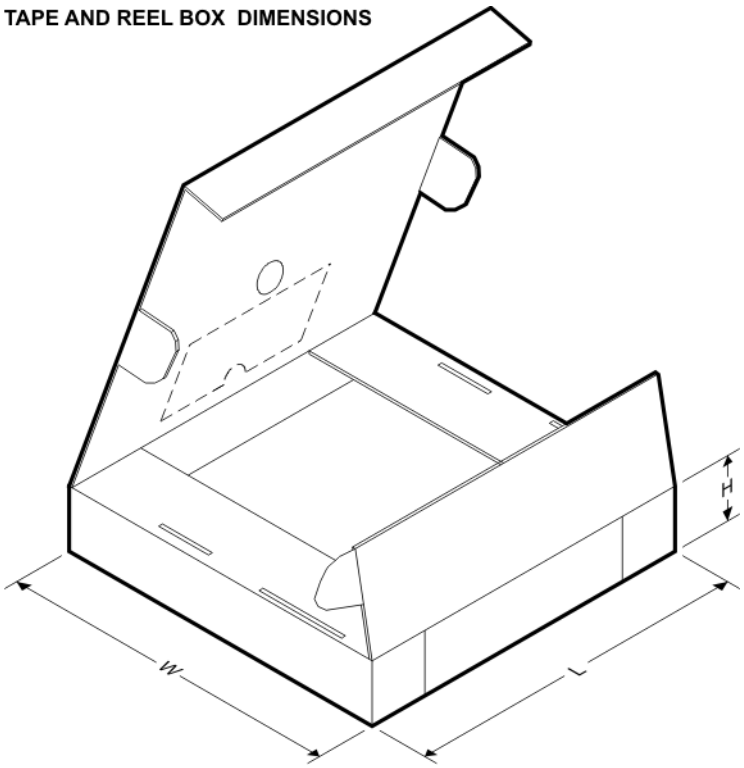
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC595DBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74AHC595DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AHC595PWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74AHC595PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHC595PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



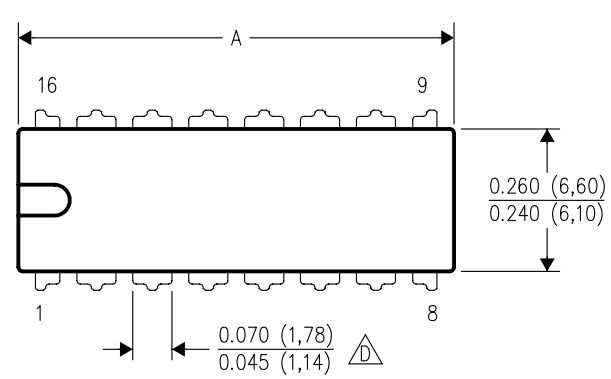
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC595DBR	SSOP	DB	16	2000	367.0	367.0	38.0
SN74AHC595DR	SOIC	D	16	2500	367.0	367.0	38.0
SN74AHC595PWR	TSSOP	PW	16	2000	364.0	364.0	27.0
SN74AHC595PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74AHC595PWRG4	TSSOP	PW	16	2000	367.0	367.0	35.0

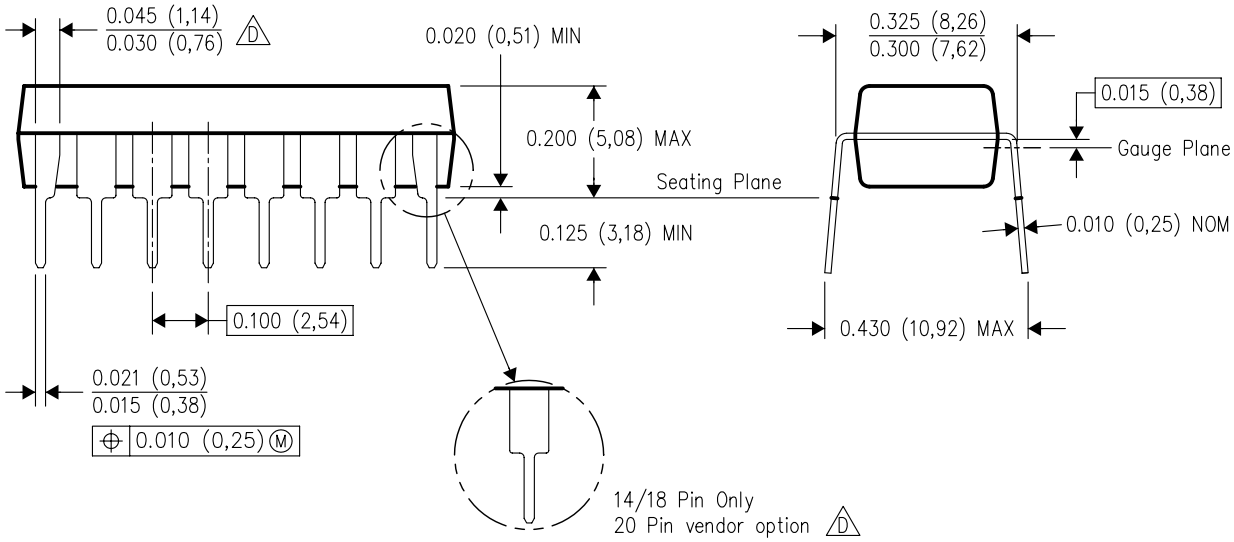
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



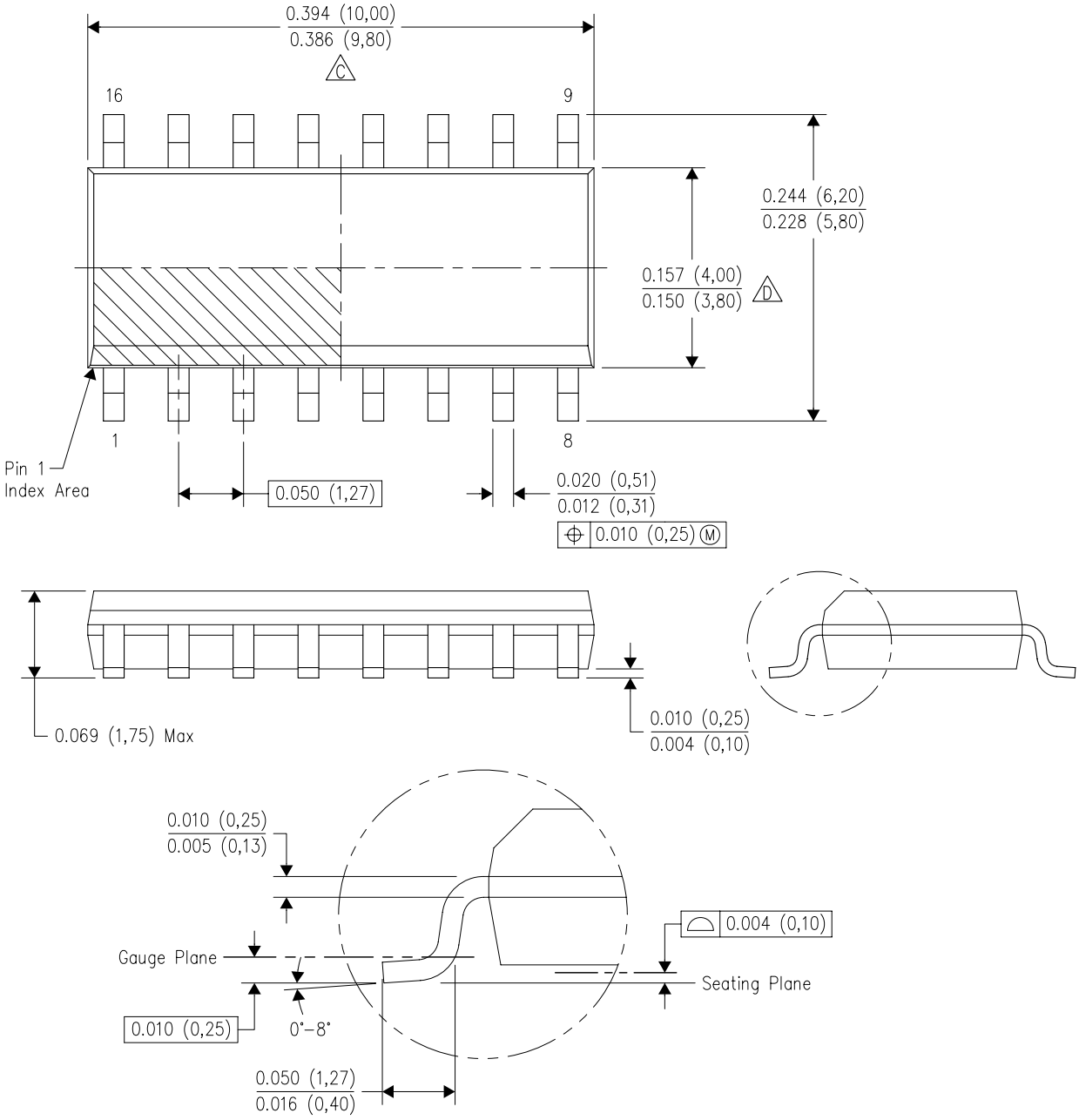
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

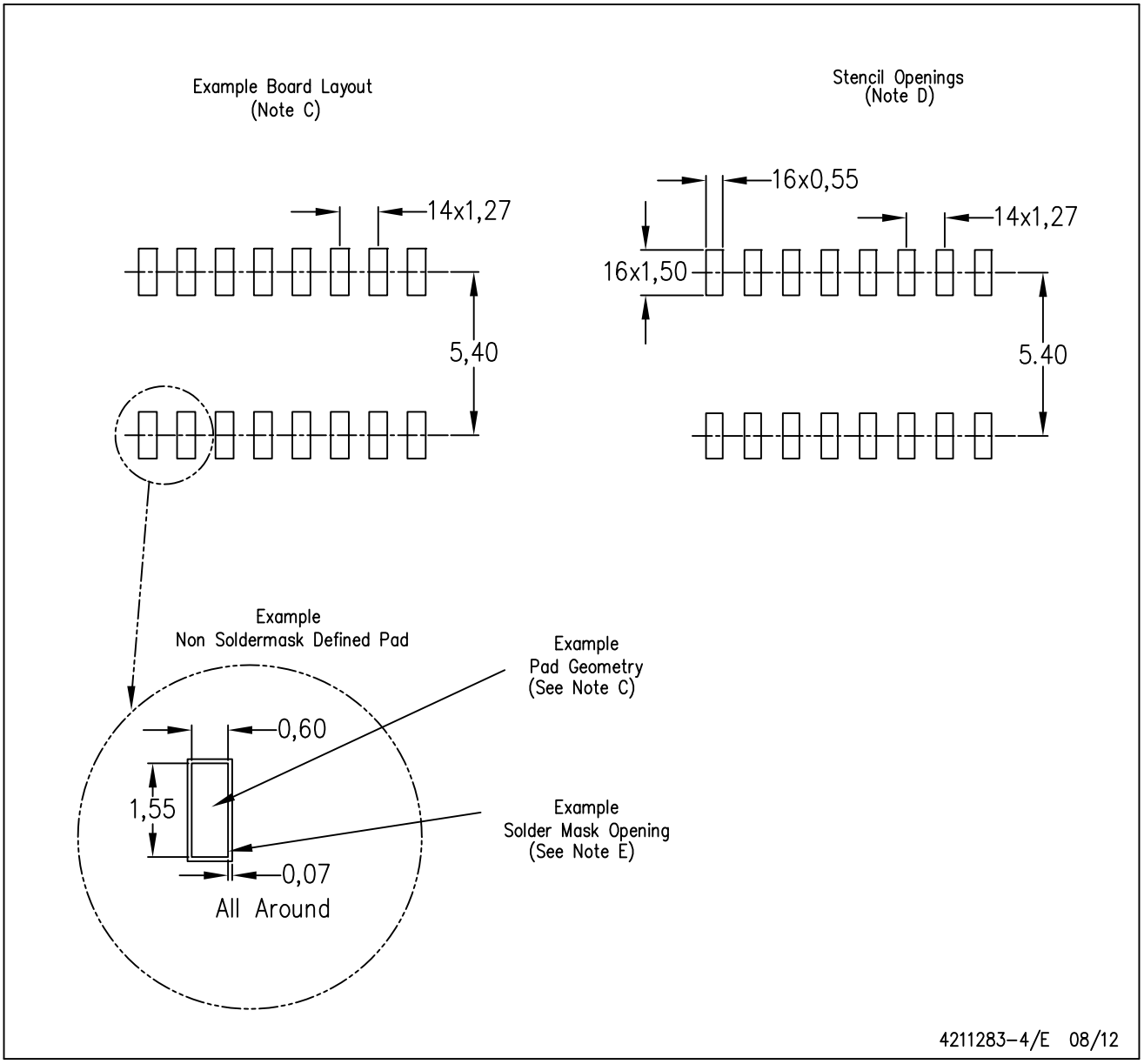
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



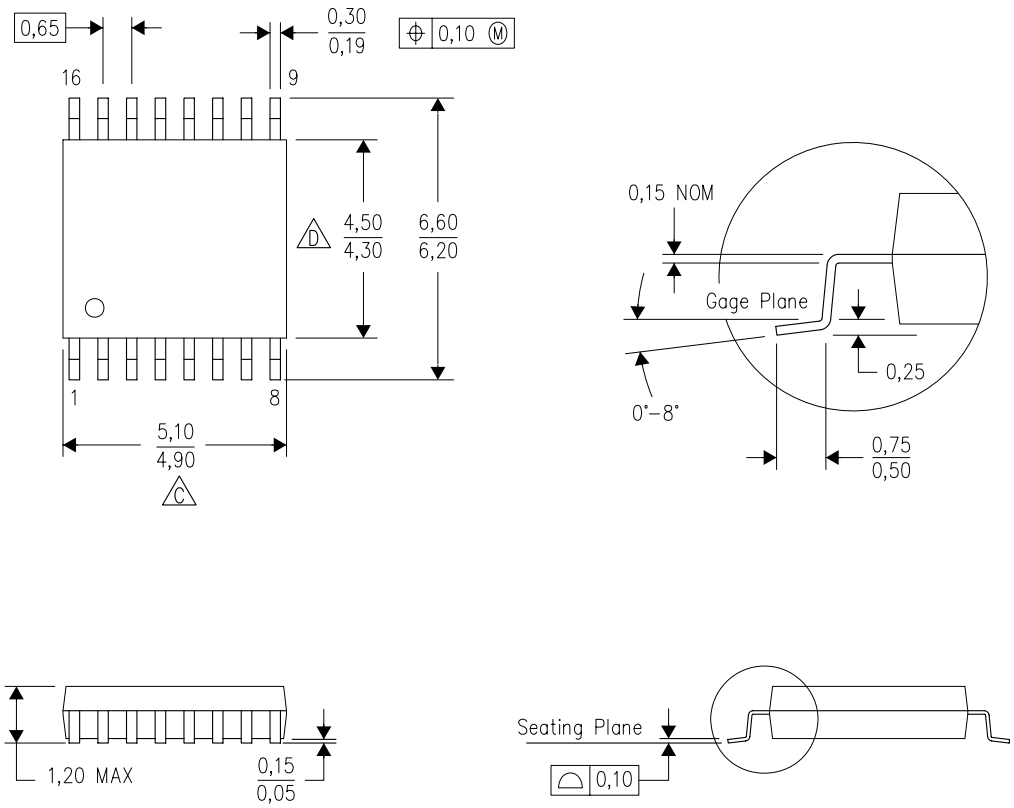
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

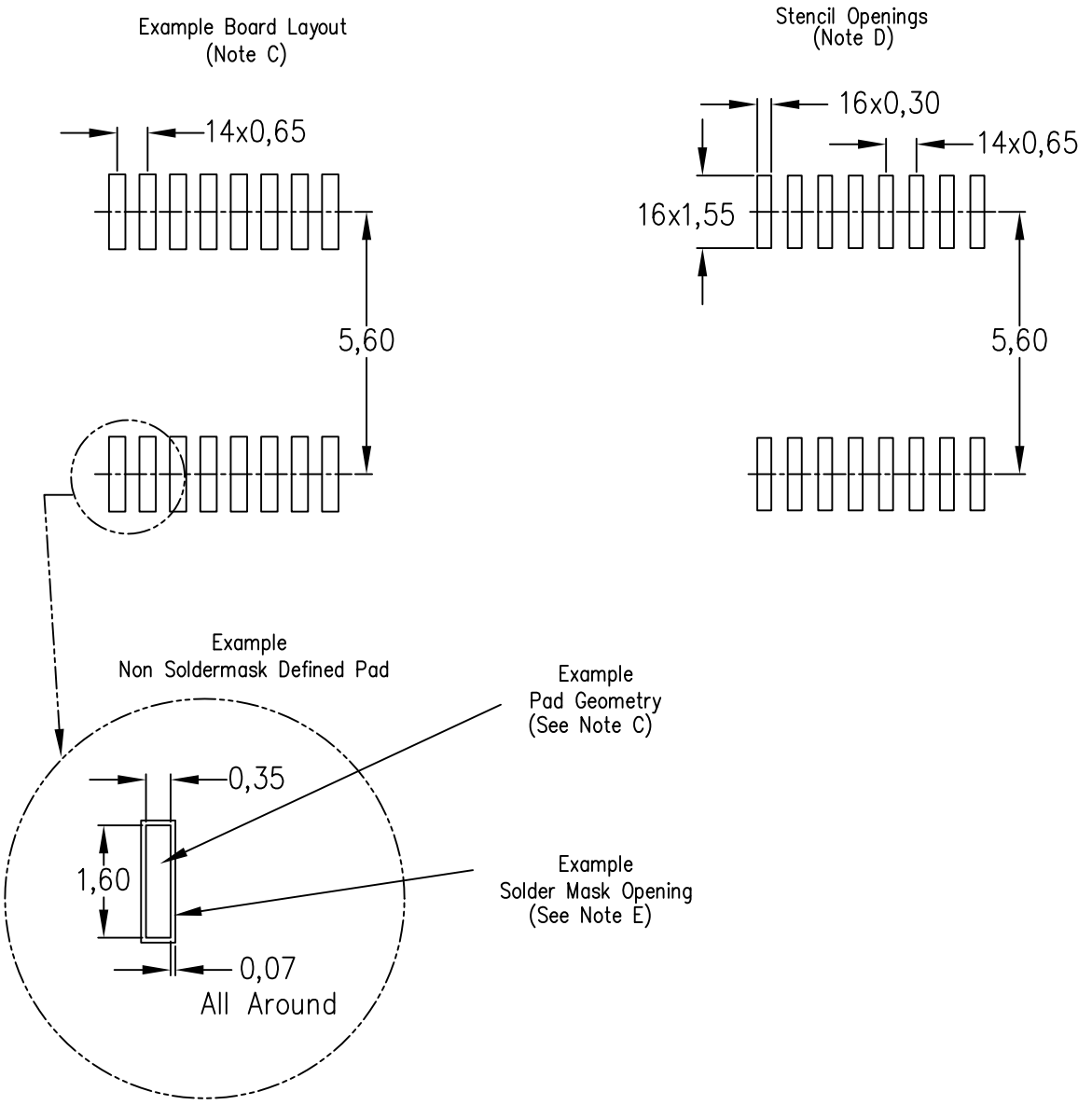
PW (R–PDSO–G16) PLASTIC SMALL OUTLINE



4040064–4/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G16) PLASTIC SMALL OUTLINE

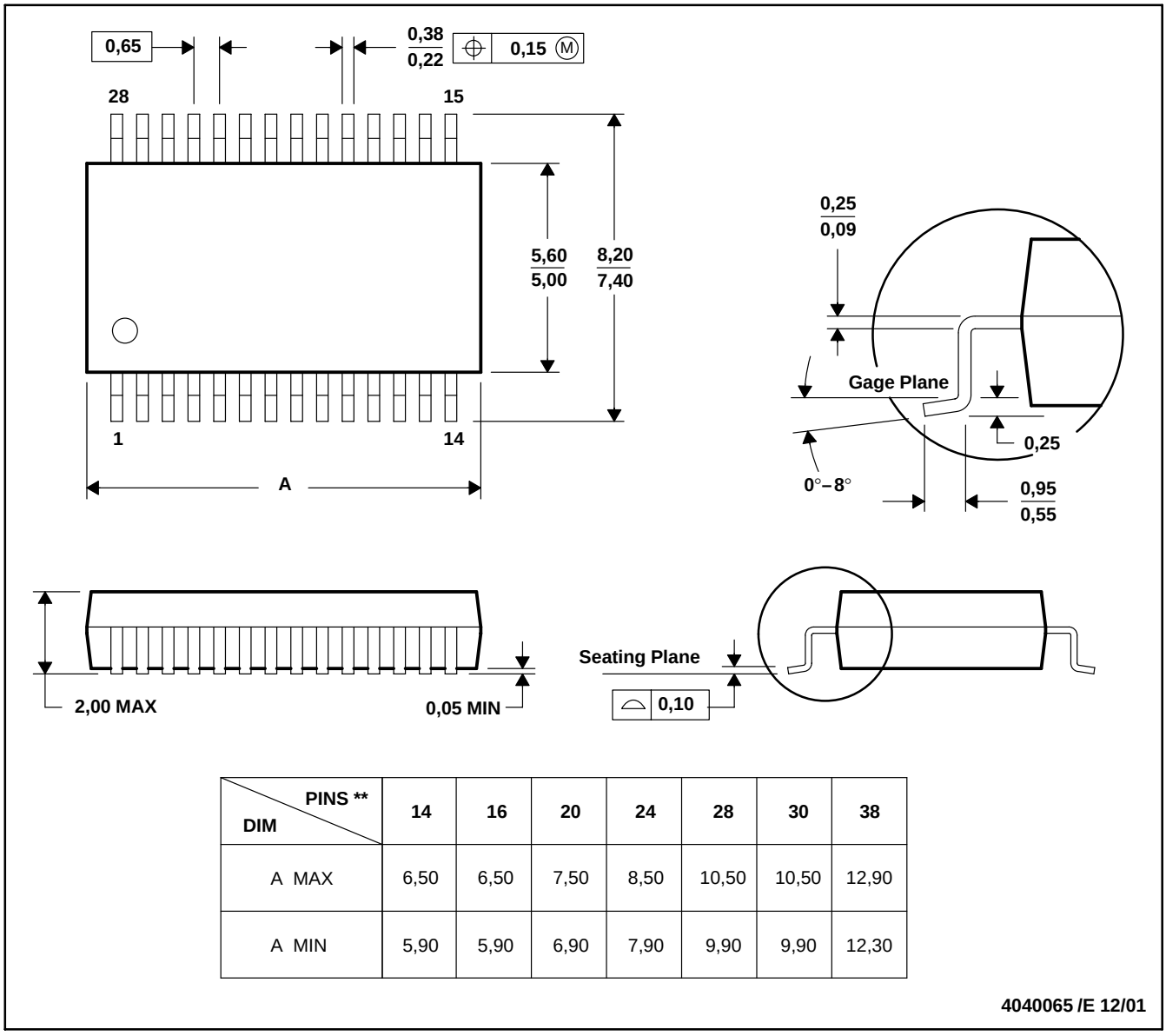


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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